

# SOT123A

CRFM4; blister pack packing method; standard product orientation 12NC ending 112

Rev. 1 — 11 October 2012

Packing information

## 1. Packing method

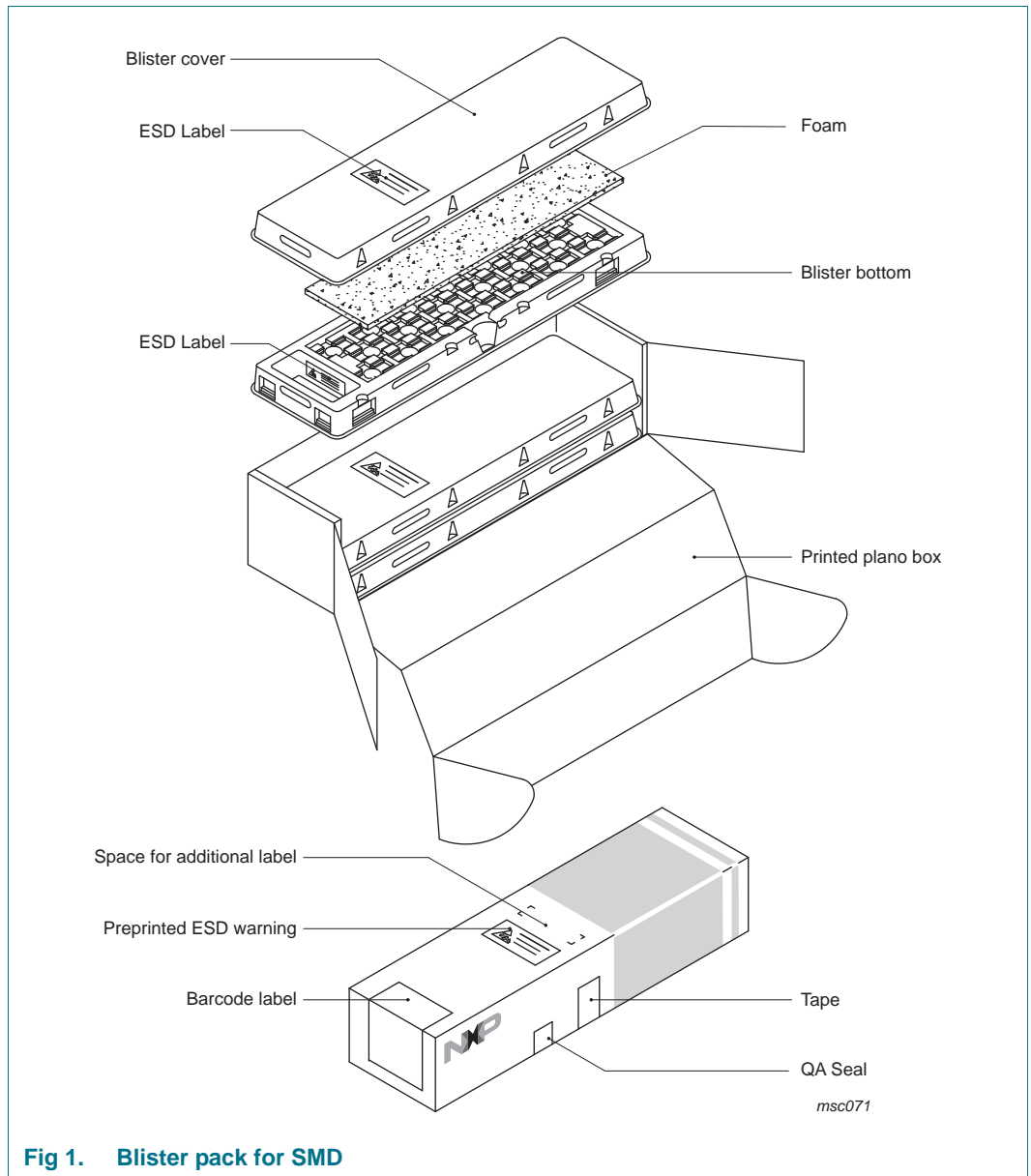


Fig 1. Blister pack for SMD

Table 1. Packing information

Package version	12NC ending	SPQ per carrier	PQ (pcs)	Carriers per box	Outer box dimensions l x w x h (mm)
SOT123A	112	20	40	2	315 x 118 x 78

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